

## UP SuperServer SYS-511E-WR

## **Key Applications**

Virtualization, Cloud Computing, Data Center Optimized, Entry GPU server, Value IaaS,

## **Key Features**

- Single Socket E (LGA-4677) 4th/5th Gen Intel® Xeon® Scalable processors. Up to 300W TDP;
- Intel<sup>®</sup> C741 Chipset;
- 8 DIMMs; Supports 3DS DDR5 RDIMM. Up to 5600 MHz;
- 2 PCIe 5.0 x16 FHFL; 1 PCIe 5.0 x8(in x16) LP; 1 PCIe 3.0 x2 NVMe M.2;
- Onboard 1G LAN ports (Intel $^{\circ}$  i210), 1 dedicated IPMI LAN;
- 4x front hot-swap 3.5" SATA3 drive bays, SAS3 with additional SAS controller card;
- Redundant Now Titanium 860W Power Supplies;





Form Factor	1U Rackmount
	Enclosure: 437 x 43 x 650mm (17.2" x 1.7" x 25.6")
	Package: 597 x 216 x 856mm (23.5" x 8.5" x 33.7")
Processor	Single Socket E (LGA-4677)
	5th Gen Intel <sup>®</sup> Xeon <sup>®</sup> /4th Gen Intel <sup>®</sup> Xeon <sup>®</sup> Scalable processors
	Up to 52C/104T; Up to 300MB Cache
GPU	Max GPU Count: Up to 1 double-width or 2 single-width GPU(s)
	Supported GPU: NVIDIA PCIe: RTX A4000,A2,L4,A10
	CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect
	GPU-GPU Interconnect: PCIe
System Memory	Slot Count: 8 DIMM slots/8 Channels
	Max Memory (1DPC): Up to 2TB 4800MT/s ECC DDR5 RDIMM
Drive Bays	4x 3.5" SATA/SAS drive bays
	1x PCle 3.0 x 2
	M-key, 2280, 22110
Expansion Slots	2 PCIe 5.0 x16 FHFL slot(s)
	1 PCIe 5.0 x8 (in x16) LP slot(s)
	Note: Acronyms: (FH = Full Height, LP = Low Profile, FL = Full Length, HL = Half Length)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support
	Chipset: Intel® C741
	Network Connectivity: 2x 1GbE BaseT with Intel <sup>®</sup> i210
	IPMI: Support for Intelligent Platform Management Interface v.2.0
	IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	SATA: 10 SATA (6Gbps) port(s)
	LAN: 2 RJ45 1GbE LAN ports
	1 RJ45 Dedicated IPMI LAN port
	USB 2.0 port(s) (2 rear; 1 Type A)
	4 USB 3.2 Gen 1 port(s) (2 rear; 2 headers)
	Video: 1 VGA port(s)
	Serial Port: 2 COM Port(s) (1 header; 1 rear)



